KOKUSAI ELECTRIC CORPORATION has made its fresh start as a pure play manufacturer of semiconductor manufacturing systems on June 1, 2018 under the capital of Kohlberg Kravis Roberts group after splitting from Hitachi Kokusai Electric Inc.

The market conditions of semiconductor are facing a major turning point as the entire semiconductor industry is experiencing a rapid demand increase by expansion of the memory market associated with a penetration of Internet of Things (IoT) to the society, growing demands of data centers and diversification of electric devices, as well as activation of the device market by artificial intelligence (AI), automated driving and currency mining, etc. The semiconductor equipment industry is also growing to the next phase along with these changes.

As we start the new company, our mission is to accommodate customers’ needs in the changing market with the leading-edge technology based on our accumulated deposition technologies and become an industry leader. We, as an innovative corporation with the customers’ perspective, are determined to move fast to provide high quality products and services, and make contribution to highly developed social infrastructures with our technology.

As always, I look forward to your continued support.

Fumiyuki Kanai
Representative Director, President and Chief Executive Officer
Semiconductors are made by forming circuits on multiple layers of films, which are coated on the surface of silicon substrates (called wafers). This process of forming thin films on wafers, called as the thermal process, is the most important phase of making semiconductors. We, KOKUSAI ELECTRIC, produce semiconductor manufacturing systems that leverages world-class coating technology such as 10nm microfabrication technology close to the physical limit, delivering to the world’s top manufacturers. Our semiconductor manufacturing systems enable the increasing high functionality and high performance of semiconductors.

Using world-class coating technology to produce high-quality semiconductor manufacturing systems

Research and development

In addition to our underlying technologies, we jointly develop next-generation high-performance semiconductor technologies with research institutions, and develop the coating technology and manufacturing technology to create them.

Design

We implement advanced technologies such as 3DCAD-based design and fluid simulations. We make the best possible use of our underlying technologies to design equipment tailored to customer needs.

Procurement

The type and number of required parts varies based on equipment model and specifications. At an automated warehouse we store over 15,000 parts obtained from various local business partners.

Manufacture

In Class 5000 Cleanrooms, we manufacture a wide range of products. We have adopted the Cell Station Production System for unit assembly to improve work efficiency, safety and productivity, and to further optimize the production scheme.

Shipment

We conduct strict product inspections and delivery inspections at every phase. Completed equipment is shipped around the world using environmentally-friendly shipping.

Installation and setup

We visit customer’s fabs, and handle everything from equipment installation to assembly, wiring, commissioning, and process launch tasks according to customer deadlines. Roughly 90% of our customers are located abroad, mainly in Asia, so many of our employees are active internationally.

Advanced Thermal Process Technology

KOKUSAI ELECTRIC is proud to introduce a novel, next-generation deposition technique, Balance Controlled Deposition (BCD®). The BCD® technique provides lower temperature processing and tighter process control for advanced small geometry devices while maintaining very high productivity, which can benefit a wide range of users and process applications.

Main Products

Batch Processing System

Single Wafer Processing System

Excellent Step Coverage

TSURUGI-C®
High-Performance Thermal Process System

AdvancedAce®-300
High-Productivity Single Wafer Processing System

VERTRON
Batch Thermal Process System for 200mm Wafers

MARORA®
Single-Wafer Plasma Nitridation / Oxidation System

TANDUO®
Single-Wafer Annealing System

Lambda300
Single-Wafer Ashing System

*BCD is a registered trademark of KOKUSAI ELECTRIC CORPORATION in Japan.

*TSURUGI-C® and AdvancedAce® are registered trademarks of KOKUSAI ELECTRIC CORPORATION.

*MARORA® and TANDUO® are registered trademarks of KOKUSAI ELECTRIC CORPORATION.
Corporate Data
(as of October 1, 2019)

Overview
Company Name KOKUSAI ELECTRIC CORPORATION
Date of Establishment February 2, 2017
Headquarters 3-4, Kandakaji-cho, Chiyoda-ku, Tokyo 101-0045, Japan
Representative Fumiyuki Kanai
Paid-in Capital ¥100 million
Fiscal Year-end September 30
Number of Employees 3,950 (non-consolidated) 1,940 (consolidated)

Organization
Board of Directors
President and Chief Executive Officer
Corporate Management Division
Strategic Management Division
Strategic Service Business Development Division
Global Field Service Engineering Division
Sales Division
Technology Development Division
Volume Equipment Engineering Division
Production Division

Corporate Governance
Directors, Corporate Auditor and Executive Officers

Directors
Fumiyuki Kanai (Representative)
Yuki Kamiya
Hiromi Kondo
Eiji Yatagawa
Masaki Nakamura

Executive Officers
Fumiyuki Kanai
Yuki Kamiya
President and Chief Executive Officer
Executive Vice President and Executive Officer
Responsible for Corporate Management, Ethics & Compliance and Information Security
Senior Vice President and Executive Officer
Responsible for Technology Development and Strategic Marketing
Corporate Vice President and Executive Officer
Responsible for Product Development, Production and Quality Assurance
Corporate Vice President and Executive Officer
Responsible for Sales

Corporate Management Division
President and Chief Executive Officer
Fumiyuki Kanai

Organization
Meetings of Shareholders
Board of Directors
Corporate Auditor
Accounting Auditor
Management Meeting

Revenues (Consolidated)
(Millions of yen)

\[
\begin{array}{|c|c|c|}
\hline
& \text{Fiscal year ended} & \text{Fiscal year ended} & \text{Fiscal year ended} \\
& \text{March 31, 2017} & \text{March 31, 2016} & \text{March 31, 2015} \\
\hline
\text{Revenue} & 91,544 & 130,976 & 160,942 \\
\hline
\end{array}
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Notes: The above values are unaudited and for reference purposes only. A fiscal year is defined as 12 consecutive months beginning April 1 and ending March 31. The consolidated financial statements for the fiscal year ended March 31, 2019 are presented in accordance with International Financial Reporting Standards (IFRS).